

## Excellent Integrated System Limited

Stocking Distributor

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[Eaton \(formerly Cooper Bussmann\)](#)  
[SDT30-127-R](#)

For any questions, you can email us directly:

[sales@integrated-circuit.com](mailto:sales@integrated-circuit.com)



# Low-Profile, Shielded Drum Core, Tapped Inductor

## SDT30 Series



### Description

- Halogen Free
- Approved for use with Maxim® MAX14521 chip set
- 125°C maximum total temperature operation
- 3.1 x 3.1 x 1.0mm shielded drum core
- Ferrite core material
- Low losses
- High efficiency
- Reduces peak output currents
- Magnetically shielded, low EMI
- RoHS compliant

### Applications

- Keypads
- Instrument clusters
- EL backlighting
- Buck or boost inductor

### Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (with derated current)
- Solder reflow temperature: J-STD-020D compliant

### Packaging

- Supplied in tape-and-reel packaging, 5000 parts per reel, 13" diameter reel
- Also supplied in tape-and-reel packaging, 7" diameter reel. See product specifications table note 5 below.



OBSOLETE  
NO RECOMMENDED  
REPLACEMENT AVAILABLE

### Product Specifications

Part Number <sup>5</sup>	Pin Numbers	OCL <sup>1</sup> (µH)	Part Marking Designator	Turns Ratio Primary:Secondary	$I_{rms}^2$	$I_{sat}^3$	DCR (mΩ) @20°C	K-factor <sup>4</sup>
					(Amps)	(Amps) @25°C		
SDT30-127-R	(1 - 2) Primary	2.9 ± 30%	A	1:7	0.60	0.85	0.41 ± 15%	856.0
	(2 - 3) Secondary	148 ± 20%			0.13	0.12	9.0 ± 15%	N/A

1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V<sub>rms</sub>, 0.0Adc

2 I<sub>rms</sub>: DC current for an approximate temperature rise of 40°C without core loss when either the primary or secondary winding is running separately. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.

3 I<sub>sat</sub>: Peak current for approximately 30% rolloff at +25°C of primary or secondary with another winding open.

4 K-factor: Used to determine B<sub>p-p</sub> for core loss (see graph). B<sub>p-p</sub> = K \* L \* ΔI. B<sub>p-p</sub>: (Gauss), K: (K-factor from table), L: (primary inductance in µH), ΔI (peak-to-peak ripple current in amps).

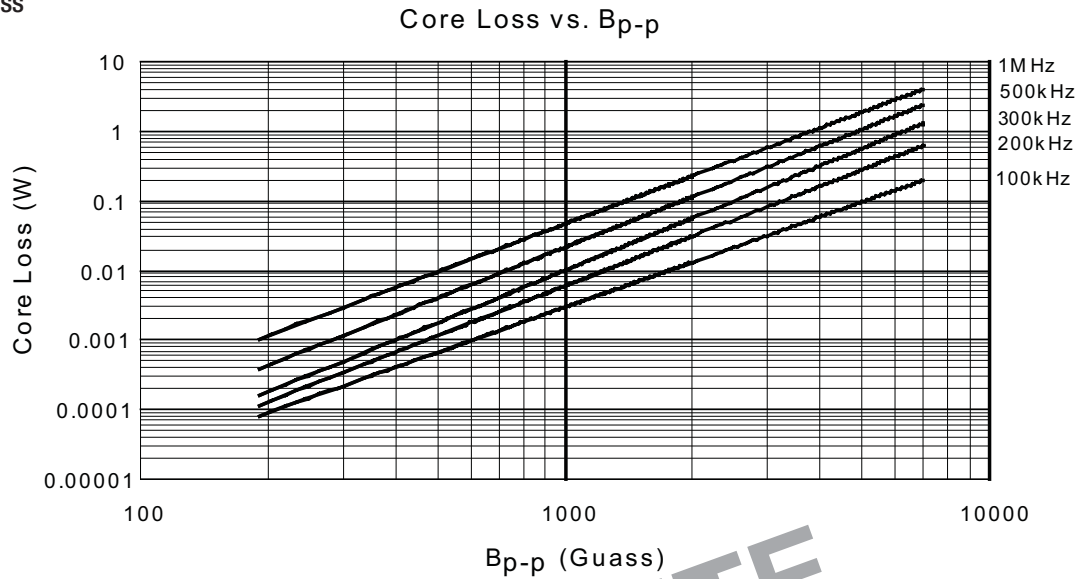
5 Part Number Definition: SDT30-x2x-yy-R

- SDT30 = Product code and size
- -x2x = Turns ratio (first "x" = primary winding, "2" = "." and second "x" = secondary winding) e.g., -127 = 1:7 primary to secondary turns ratio.
- -yy = add "T7" for 7 inch tape-and-reel package. Leave blank for 5000 parts on 13 inch tape-and-reel package.
- "-R" suffix = RoHS compliant

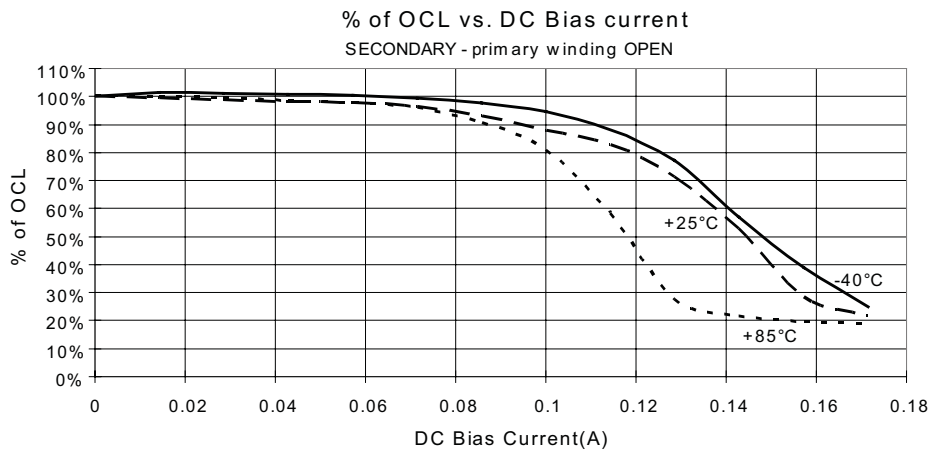
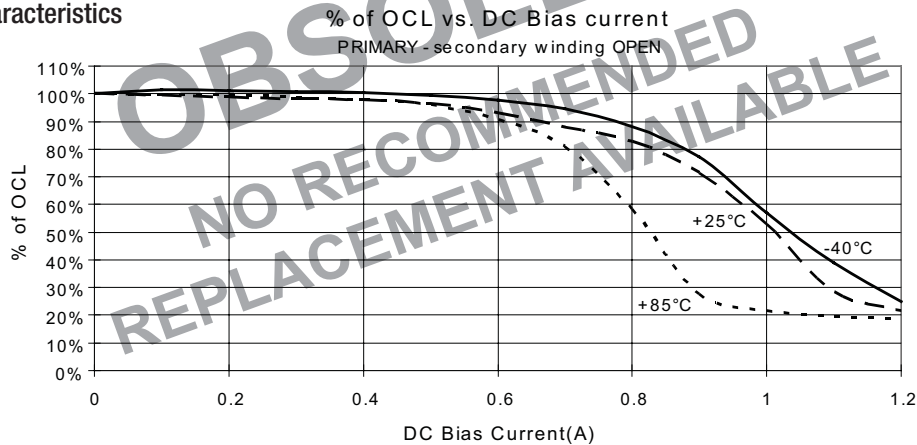




Core Loss



Inductance Characteristics





### Solder Reflow Profile

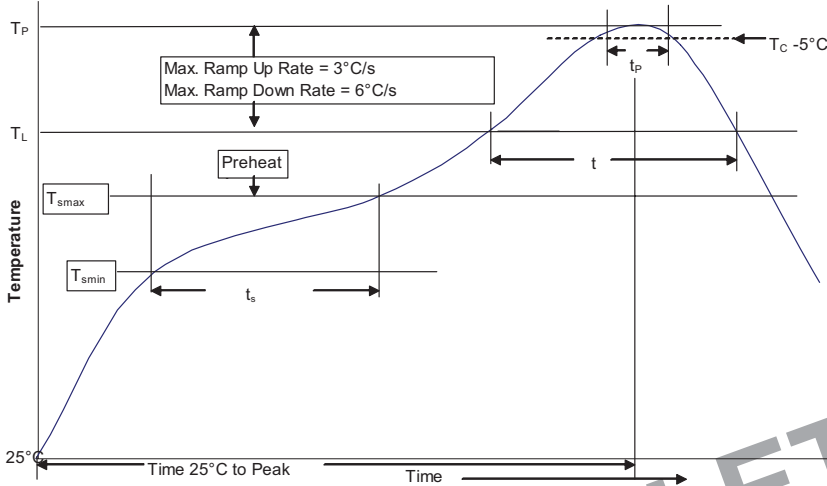


Table 1 - Standard SnPb Solder ( $T_c$ )

Package Thickness	Volume $\leq 350$ mm <sup>3</sup>	Volume $\geq 350$ mm <sup>3</sup>
<2.5mm	235°C	220°C
$\geq 2.5$ mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder ( $T_c$ )

Package Thickness	Volume $\leq 350$ mm <sup>3</sup>	Volume 350 - 2000 mm <sup>3</sup>	Volume $> 2000$ mm <sup>3</sup>
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
$> 2.5$ mm	250°C	245°C	245°C

### Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. ( $T_{smin}$ )	100°C	150°C
• Temperature max. ( $T_{smax}$ )	150°C	200°C
• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 Seconds	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_p$	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature ( $T_L$ )	183°C	217°C
Time at liquidous ( $t_l$ )	60-150 Seconds	60-150 Seconds
Peak package body temperature ( $T_p$ )*	Table 1	Table 2
Time ( $t_p$ )** within 5 °C of the specified classification temperature ( $T_c$ )	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

#### North America

Cooper Electronic Technologies  
 1225 Broken Sound Parkway NW  
 Suite F  
 Boca Raton, FL 33487-3533  
 Tel: 1-561-998-4100  
 Fax: 1-561-241-6640  
 Toll Free: 1-888-414-2645

Cooper Bussmann  
 P.O. Box 14460  
 St. Louis, MO 63178-4460  
 Tel: 1-636-394-2877  
 Fax: 1-636-527-1607

#### Europe

Cooper Electronic Technologies  
 Cooper (UK) Limited  
 Burton-on-the-Wolds  
 Leicestershire • LE12 5TH UK  
 Tel: +44 (0) 1509 882 737  
 Fax: +44 (0) 1509 882 786

Cooper Electronic Technologies  
 Avda. Santa Eulalia, 290  
 08223  
 Terrassa, (Barcelona), Spain  
 Tel: +34 937 362 812  
 +34 937 362 813  
 Fax: +34 937 362 719

#### Asia Pacific

Cooper Electronic Technologies  
 1 Jalan Kilang Timor  
 #06-01 Pacific Tech Centre  
 Singapore 159303  
 Tel: +65 278 6151  
 Fax: +65 270 4160

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